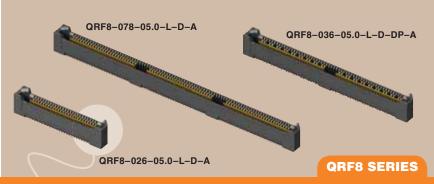




(0,80 mm) .0315"



SLIM BODY GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QRF8

Insulator Material: Black LCF

Contact Material:

BeCu

Ground Plane Material:

Phosphor Bronze

Plating: Au or Sn over 50μ" (1,27 μm) Ni

Current Rating:

Contact: 2.2 A per pin

(1 pin powered per row) Ground Plane:

8.5 A per ground plane

(1 ground plane powered)
Operating Temp Range:

-55°C to +125°C Voltage Rating:

RoHS Compliant: Yes

Processing:

Lead-Free Solderable:

SMT Lead Coplanarity: (0,10 mm) .004" max (018-026) (0,15 mm) .006" max (036-078)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT*			
QRF8 LEAD	QRM8 LEAD STYLE		
STYLE		-05.0	
-05.0	(7,00) .276	(10,00) .394	(12,00) .472
-07.0	(9,00) .354	(12,00) .472	(14,00) .551
45			

Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

 Other platings Contact Samtec.

Note: Patented

Note: Some lengths, styles and options are non-standard, non-returnable.



-026, -052, -078(52 total pins per bank = -D)

QRF8

available at www.samtec.com?QRF8 or contact sig@samtec.com

PINS PER ROW

NO. OF PAIRS

-018, -036, -054 (18 pairs per bank = -D-DP)

05.0 = 5 mm Body Height

STYLE

-07.0 = 7 mm Body Height

No. of Banks x (24,80) .976 + (3,57) .140

= 10 µ' (0,25 µm) Gold on contact, **Matte Tin** on tail

PLATING

OPTION

-D Single-Ended -D–DP = Differential Pair

.041

TYPE

–GP

= Guide Post (Requires -GP on mating connector)

OTHER

OPTION

(5,00 mm) .197" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel (-018, -026, 036, -052 only)

RUGGEDIZED

SAMTEC

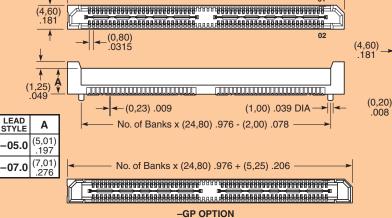
Increased contact

· Guide post option

Edge Rate[™] contacts

10 year MFG

wipe



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM